

1FWS



501.43630X00

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s): N. KAWANABE, et al  
Serial No.: 10/807,249  
Filed: March 24, 2004  
For: A METHOD OF MANUFACTURING A SEMICONDUCTOR  
DEVICE TO PROVIDE IMPROVED ADHESION BETWEEN  
BONDING AND BALL PORTIONS OF ELECTRICAL  
CONNECTORS (as amended)

Group:

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

May 5, 2004

Sir:

The following preliminary amendments and remarks are respectfully  
submitted in connection with the above-identified application, as listed below and as  
set forth on the following pages:

Substitute Specification and Marked Up Version of Original Specification;  
Amendment of the Abstract; and  
Remarks are included following the amendments.